Yuan Yao

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Education

·Jilin University, China

2021.9-now

Bachelor of Engineering, School of mechanical and aerospace engineering Overall score: 90.62/100, rank within top 5%

·Tohoku University, Japan

2023.10-2024.8

Exchange student, Department of Robotics

8/9 Course grades: A/ AA

Research experiences

 ${\bf \cdot} Exploration \ of \ Film \ Separation \ Technique \ by \ Internal \ Laser \ Damage$

2023.10-2024.8

Advised by Prof. Shuji Tanaka and Prof. Andrea Vergara

MEMS lab, Tohoku University

- ♦ A two-dimensional laser **stealth dicing** method for **low-stress separation of silicon-based thin films** is innovatively implemented, verifying its feasibility in the **transfer of flexible piezoelectric devices**. The output was presented at MNC2024 and expanded to the a journal paper (expected).
- ♦ Experienced in cleanroom workflows and equipment operation, including: Mask design/fabrication, Photolithography, DRIE, PVD/CVD, Dicing, Laser systems, and Optical/SEM/Infrared microscopy. More
- •Ultrasonic vibration-assisted scratch testing platform: design and study Advised by Prof. Hu Huang

2022.9-2024.4 Huang lab, Jilin University

- ♦ Design and verify the thread-V groove composite structure to ensure effective vibration transmission; match the system's resonance frequency with the ultrasonic transducer working frequency through Abaqus modal simulation. Fills the gap for instruments that can perform scratch testing under ultrasonic vibration.
- ♦ National Undergraduate Training Program for Innovation and Entrepreneurship(NCSIETP), **National Excellent Conclusion.** Derived 1 utility model patent and 1 journal paper. More

Academic achievement

- A paper submitted (conference extended): **Yao, Y.**, Vergara, A., Tang, Z. & Tanaka, S. Feasibility study of layer separation using 2D patterned internal laser damage in silicon. *IEEJ Transactions on Electrical and Electronic Engineering*
- •Oral presentation on the 37th International Microprocesses and Nanotechnology Conference (MNC 2024), Kyoto: The Japan Society of Applied Physics, Nov. 2024, 15D-2-3. Slide Abstract
- Journal paper published: Huang, Y.; Wu, H.; Yao, Y.; Zhao, H.; Huang, H. An Ultrasonic Vibration Scratch Tester for Studying the Scratch Characteristics of Materials under Ultrasonic Vibration Contact Status. *Actuators* 2024, 13, 262. https://doi.org/10.3390/act13070262
- Utility Model Patent published: H. Huang, Y. Yao, Y. Huang, and H. Wu, "An ultrasonic vibration device for vibration-assisted scratch testing," Chinese Patent CN 220649966U, Mar. 22, 2024. Patent

Skills

- •Languages: Native Mandarin; Fluent English including IELTs: 7.0 (6.5), CET4: 622, CET6: 559, GRE: 320; Basic Japanese
- Professional Software: <u>Proficient</u>: Solidworks, Autocad; <u>Intermediate</u>: Catia; Ansys, Abaqus, Recurdyn; Matlab Simulink, Origin
- •Basic Programming Skills: Python, Matlab, C#, LATEX

Awards and Honors

National second prize- National University Students' Advanced Drawing Technology and Product

- Information Modeling Innovation Competition
 - ♦ Advanced Engineering drawing; Proficient in CAD software; Teaching of the competition More 2022.8

Provincial first prize - China College Students Engineering Practice and Innovation Competition

♦ Led the design and manufacture of a new energy mini-vehicle More

2023.11

• Exchange student scholarship - Japan Student Services Organization

2023.10-2024.8

• First-class scholarship; Excellent student - Jilin University

2023.11/2022.11

• Excellent student leader - School of Mechanical and Aerospace Engineering, Jilin University 2022.11